

| SYMBOL | MILLIMETERS | | | NOTE |
|--------------------------------|-------------|----------|-------|------|
| | MIN. | NOM. | MAX. | |
| A | <i>h</i> | 2.23 | 2.43 | 2 |
| A ₁ | 0.40 | 0.50 | 0.60 | |
| D/E | 20.80 | 21.00 | 21.20 | |
| D ₁ /E ₁ | 19.00 REF | | | |
| e | 1.00 BSC | | | |
| ø _b | 0.50 | 0.60 | 0.70 | |
| aaa | <i>h</i> | <i>h</i> | 0.20 | |
| ccc | <i>h</i> | <i>h</i> | 0.35 | |
| ddd | <i>h</i> | <i>h</i> | 0.25 | |
| eee | <i>h</i> | <i>h</i> | 0.10 | |
| M | 20 | | | |

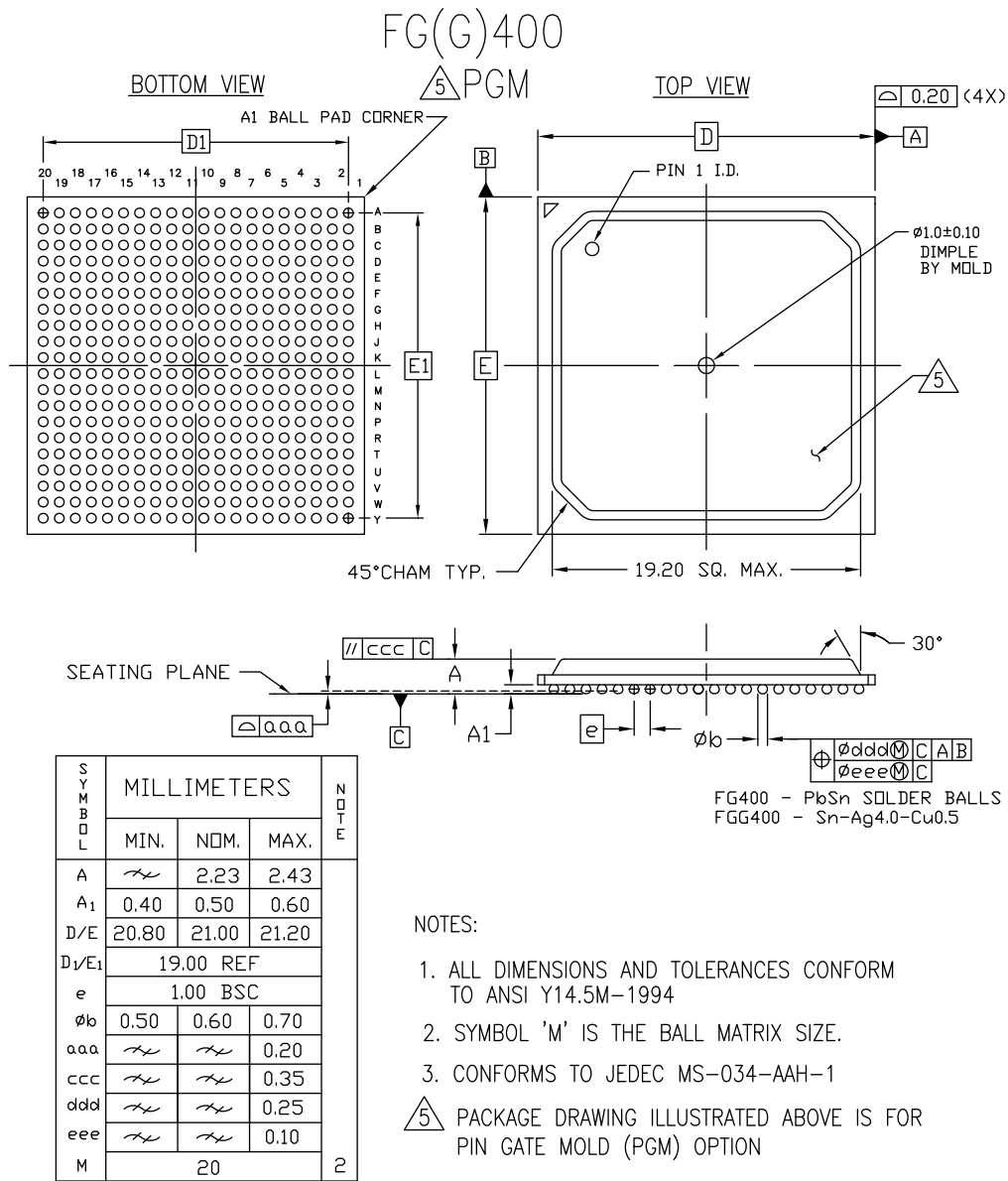
FG400 - PbSn SOLDER BALLS
 FGG400 - Sn-Ag4.0-Cu0.5

NOTES:

- ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
- SYMBOL 'M' IS THE BALL MATRIX SIZE.
- CONFORMS TO JEDEC MS-034-AAH-1
- PACKAGE DRAWING ILLUSTRATED ABOVE IS FOR CORNER GATE MOLD (CGM)
- SEE NEXT PAGE FOR PIN GATE MOLD (PGM) OPTION

pk083_01_032114

Figure 1: Corner Gate Mold Option, FG400/FGG400 Package



pk083_02_032114

Figure 2: Pin Gate Mold Option, FG400/FGG400 Package

Revision History

The following table shows the revision history for this document.

| Date | Version | Description of Revisions |
|------------|---------|---|
| 03/01/2005 | 1.0 | Initial Xilinx release. |
| 04/04/2014 | 1.1 | Added Figure 2 , pin gate mold package as described in XCN12023 . |

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